TOSHIBA Field-Effect Transistor Silicon N-Channel MOS Type

# SSM6K209FE

- High-Speed Switching Applications
- O Power Management Switch Applications

4.0V drive

• Low ON-resistance:  $R_{on}$  = 145m $\Omega$  (max) (@V<sub>GS</sub> = 4.0 V)  $R_{on}$  = 74m $\Omega$  (max) (@V<sub>GS</sub> = 10 V)

### **Absolute Maximum Ratings (Ta = 25°C)**

Characteristic	Symbol	Rating	Unit		
Drain-source voltage	V <sub>DSS</sub>	30	V		
Gate-source voltage	V <sub>GSS</sub>	± 20	V		
Drain current	DC	I <sub>D</sub>	2.5	Α	
	Pulse	I <sub>DP</sub>	5.0		
Drain power dissipation	P <sub>D</sub> (Note 1)	500	mW		
Channel temperature	T <sub>ch</sub>	150	°C		
Storage temperature	T <sub>stg</sub>	<b>−55~150</b>	°C		

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on an FR4 board (25.4 mm  $\times$  25.4 mm  $\times$  1.6 t, Cu Pad: 645 mm<sup>2</sup>)

# 1.6±0.05 1.2±0.05 1.2±0.05 5 00+0.1 2.5, 6: Drain 3 : Gate ES6 4 : Source JEDEC — JEITA — TOSHIBA 2-2N1A

Weight: 3.0 mg (typ.)

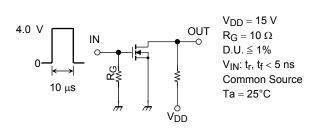
### **Electrical Characteristics (Ta = 25°C)**

Chara	ecteristic	Symbol	Test Condition		Min	Тур.	Max	Unit
Drain–source breakdown voltage		V (BR) DSS	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$		30	_	_	V
		V (BR) DSX	$I_D = 1 \text{ mA}, V_{GS} = -20 \text{ V}$		15	_	_	V
Drain cutoff currer	nt	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V		_	_	1	μА
Gate leakage curr	ent	I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$		_		±1	μА
Gate threshold vo	Itage	V <sub>th</sub>	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 1 mA		1.2	_	2.6	V
Forward transfer a	admittance	Y <sub>fs</sub>	$V_{DS} = 5 \text{ V}, I_D = 1.5 \text{ A}$ (Not	e2)	2.7	5.3	_	S
Drain-source ON-resistance		Б	$I_D = 1.5 \text{ A}, V_{GS} = 10 \text{ V}$ (Not	e2)	_	54	74	mΩ
		R <sub>DS</sub> (ON)	$I_D = 1.0 \text{ A}, V_{GS} = 4.0 \text{ V}$ (Not	e2)		85	145	
Input capacitance		C <sub>iss</sub>			_	320	_	
Output capacitance Reverse transfer capacitance		Coss	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		_	55	_	pF
		C <sub>rss</sub>			_	44	_	
Total Gate Charge		$Q_g$	V 45V L 0.5 A		_	7.7	_	
Gate-Source Charge		$Q_{gs}$	V <sub>DS</sub> = 15V, I <sub>D</sub> = 2.5 A			6.0	_	nC
Gate-Drain Charge		$Q_{gd}$	V <sub>GS</sub> = 10 V		_	1.7	_	
Switching time	Turn-on time	t <sub>on</sub>	V <sub>DD</sub> = 15 V, I <sub>D</sub> = 1.0 A,		_	17	_	
	Turn-off time	t <sub>off</sub>	$V_{GS} = 0~4.0 \text{ V}, R_{G} = 10 \Omega$		_	12	_	ns
Drain–source forward voltage		V <sub>DSF</sub>	$I_D = -2.5 \text{ A}, V_{GS} = 0 \text{ V}$ (Note2)		_	-0.9	-1.2	V

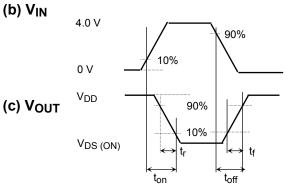
Note 2: Pulse test

# **Switching Time Test Circuit**

### (a) Test Circuit

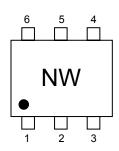


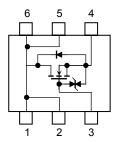
### (b) V<sub>IN</sub>



### Marking

## **Equivalent Circuit (top view)**





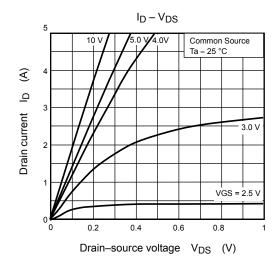
### **Notice on Usage**

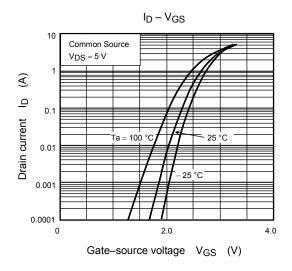
Vth can be expressed as the voltage between gate and source when the low operating current value is ID = 1 mA for this product. For normal switching operation, VGS (on) requires a higher voltage than Vth and VGS (off) requires a lower voltage than  $V_{th}$ . (The relationship can be established as follows:  $V_{GS (off)} < V_{th} < V_{GS (on)}$ .)

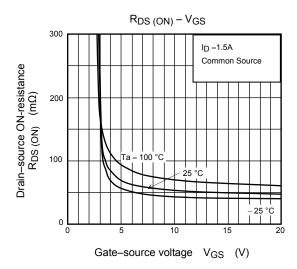
Take this into consideration when using the device.

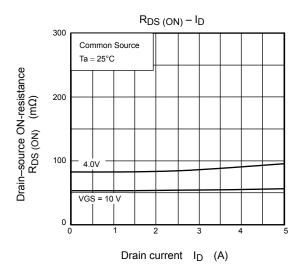
### **Handling Precaution**

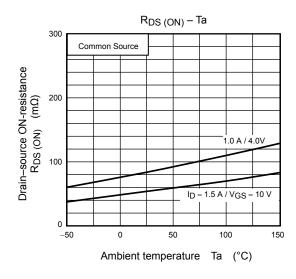
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

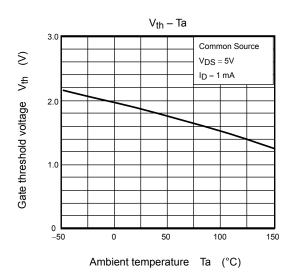


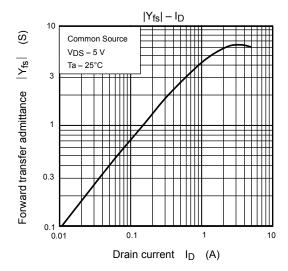


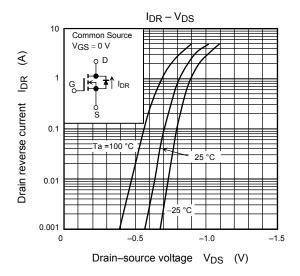


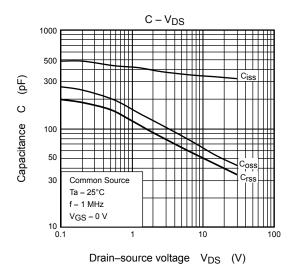


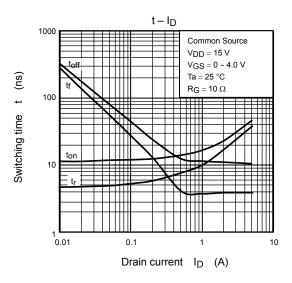


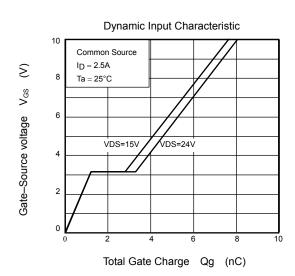


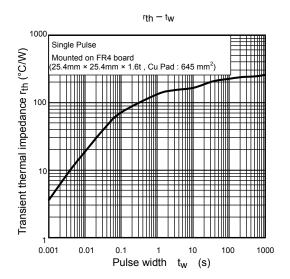


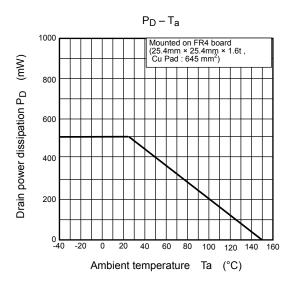












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20070701-EN GENERAL

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